

RESIN SEALED TYPE SEMICONDUCTOR DEVICE

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Abstract

PURPOSE: To protect outer leads against deformation such as bend and to prevent soldering from deteriorating in reliability by a method wherein a support protruding from the side face of the outer lead toward an adjacent outer lead and insulators provided between the adjacent supports so as to connect them together are provided.

CONSTITUTION: A lead frame is provided with inner leads 2 provided around an island 1, outer leads 4 provided outside a resin sealed region 3 and connected to the inner leads 2, a tie bar 5 provided near the resin sealed region 3 to support the outer leads 4 interlinking them together, a support 6 whose ends are projected and recessed so as to enable them to be engaged with each other and which protrude from the side face of the outer lead 4 distant from a resin sealed region toward the adjacent outer lead 4, and an insulator 7 provided to be interposed between the adjacent supports 6 so as to interlink the supports 6 together. By this setup, leads can be protected against deformation caused by external shock and improved in reliability of soldering at mounting.

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